

# ESREF 2014 IN BERLIN

Christian Boit, Technische Universität Berlin, ESREF 2014 General Chair  
christian.boit@tu-berlin.de



## ESREF 2014 conference venue at TU Berlin

The 25th anniversary of the European Symposium on Reliability of Electron Devices, Failure Physics and Analysis (ESREF) was held September 29 to October 2, 2014, in Berlin, Germany.

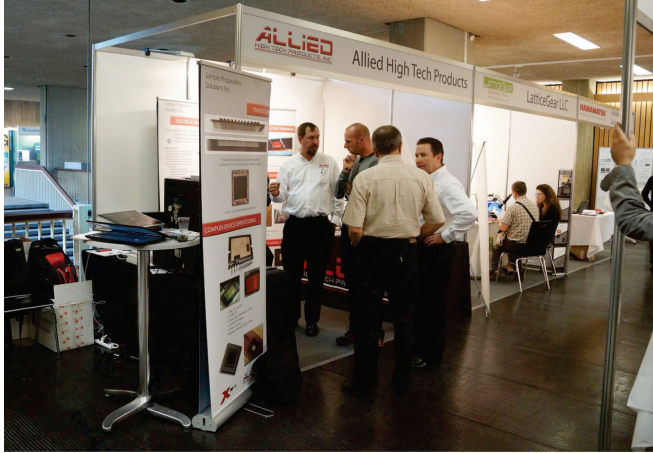
The conference has come a long way in attracting attendees. As always, the key is the organizers. The Program Committee, chaired by Eckhard Langer (Globalfoundries) and Eckhard Wolfgang (ECPE), set up a very strong program that was condensed to three days plus the opening and included the European FIB User Group (EFUG). Jan Gaudestad (Neocera), chair of the Equipment Exhibition, did an incredible job of integrating the Expo booths into the conference activities. Philippe Perdu (CNES) and Jerome Touzel (Infineon) closely tied the tutorials and workshops to the technical sessions, thus creating five very successful topical tracks. Thanks to the helping hands from VDE (Jasmin Kayadelen, Christian Groß, and Volker Schanz),

the organization, financial control, and budgetary matters were handled in a very commendable manner. Thanks also go to Technische Universität Berlin (TU Berlin) for providing a venue with a free and easy atmosphere. Last but certainly not least, Philipp Scholz (TU Berlin) provided an incommensurable contribution: He put forth the “face” that ESREF 2014 offered to the contributors and participants by designing the bag and coordinating the conference brochure and flyers, the online communication and publications, the smartphone app, and much more. I also must thank my department co-workers, and a hearty thank you goes to our sponsors, who enabled us to “smarten up” the conference.

The dynamic potential of Berlin can best be described by the term *city of the unexpected*. The organizers of ESREF 2014 did their part by making the conference itself an unexpected one—unexpectedly productive with the aforementioned five topical



ESREF 2014 Author's Gallery



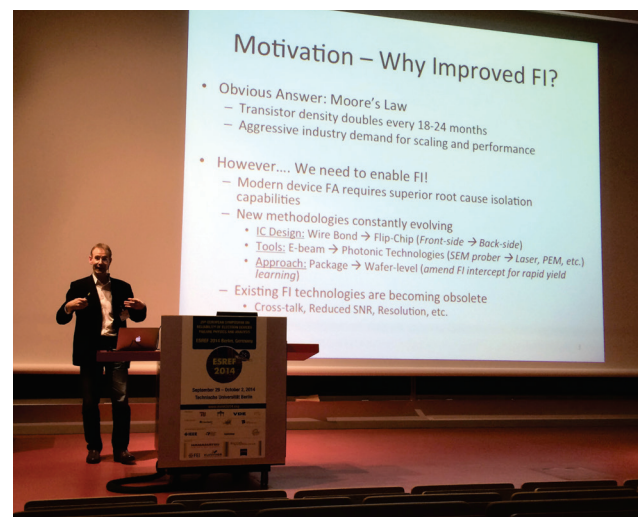
ESREF 2014 Equipment Exhibition

tracks and the special merging of tutorials, sessions, and workshops. While focusing on rapidly growing topics such as organic devices, 3-D packaging, and wide-bandgap (power) devices, the conference was solidly grounded in industry-oriented fundamentals of microelectronics, power devices, and the respective failure analysis. For the first time, EFUG was integrated as one large topical track in the conference program. In addition to the five topical tracks, there were four tutorials, three workshops, and a total of eight invited presentations, which created quite an innovative and well-structured program.

The main focus in 2014 was organic devices. Two keynote speeches highlighting aspects from industry and research institutes brought the significant progress in the world of organic devices to the ESREF community. On the other hand, a topical track on organic devices, composed of tutorials, an invited presentation, a session, and a workshop, created awareness within the organic device community that ESREF is the right place to communicate about reliability and failure analysis.

The ESREF 2014 Technical Program was defined by the Technical Program Committee, which was organized into ten subcommittees devoted to the various aspects of reliability physics and failure analysis, respectively. The presented papers were the result of a strict preselection

from 248 extended summaries, followed by an extensive peer review and mentoring action supported by more than 150 specialists. The Technical Program Committee selected 92 works to be presented as oral papers and 55 as posters. This conference would not have been possible without the commitment and expertise of all these contributors. The ESREF 2014 Proceedings were published in *Microelectronics Reliability* (Volume 54, Issues 9-10, Sept.-Oct. 2014).

ESREF 2014 failure analysis session invited speaker  
Derryck Reid

Two major ESREF innovations were introduced in Berlin. An Author's Gallery, a posted wall for the oral presenters, was organized to foster intense exchange about the presentations during the session breaks. In addition, a smartphone app was available for advanced interaction throughout the program, easier communication with the exhibitors, and other special features that made ESREF 2014 a very contemporary conference.

The social event was held at the Kulturbrauerei, a very Berlin-specific venue, and offered a unique atmosphere due to its 19th century industrial-age architecture combined with the avant-garde interior of an international pace-setting Berlin club scene.

The variety available at ESREF 2014 inspired the 350 participants. The conference organizers were very satisfied with the positive feedback, and they look forward to passing along the conference spirit to the organizing committee for ESREF 2015 in Toulouse, France. ■



ESREF 2014 at the Technische Universität Berlin in Germany



## NOTEWORTHY NEWS

### ESREF 2015

The 26th European Symposium on Reliability of Electron Devices (ESREF '15) will take place **October 5 to 9, 2015**, in Toulouse, France, the world center for aeronautics, the European capital of the space industry, and France's leader for embedded electronic systems. This international symposium continues to focus on recent developments and future directions in quality and reliability management of materials, devices, and circuits for micro-, nano-, and optoelectronics. This year's conference includes the aeronautics, space, and embedded systems industries and such topics as radiation hardening, very long-term reliability, high-/low-temperature challenges, obsolescence and counterfeit issues, wide-bandgap power devices for electric aircraft, and other embedded system applications. ESREF provides a European forum for developing all aspects of reliability management and innovative analysis techniques for present and future electronic applications.

For more information, visit [esref2015.org](http://esref2015.org). ■

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